NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5-1982.
2. DATUM PLANE -H- LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT BOTTOM OF PARTING LINE.
3. DATUMS A-B AND -D- TO BE DETERMINED WHERE CENTERLINE BETWEEN LEADS EXITS PLASTIC BODY AT DATUM PLANE -H- .
4. TO BE DETERMINED AT SEATING PLANE -C- .
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS .010"/0.254mm ON D1 AND E1 DIMENSIONS.
6. "N" IS THE TOTAL NUMBER OF TERMINALS.
7. THESE DIMENSIONS TO BE DETERMINED AT DATUM PLANE -H- .
8. PACKAGE TOP DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS BY 0.20(.008) MILLIMETERS.
9. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm/.003" TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT.
10. CONTROLLING DIMENSION: MILLIMETER. INCHES ARE IN "( )".
11. MAXIMUM ALLOWABLE DIE THICKNESS TO BE ASSEMBLED IN THIS PKG. FAMILY IS 0.635 MILLIMETERS.
12. THIS DRAWING CONFORMS TO JEDEC REGISTERED OUTLINE MO-112., EXCEPT THE FORM RADIUS "R".

LD CNT.	ANAM/AMKOR	JEDEC
44	BA	AA-2
52	BB	AC-2

VARIATIONS ALL DIMENSIONS IN MILLIMETERS

SYMBOL	BA MIN.	BA NOM.	BA MAX.	NOTE	BB MIN.	BB NOM.	BB MAX.	NOTE
A		2.13	2.35			2.13	2.35	
A_1	0.10	0.15	0.25		0.00	0.15	0.25	
A_2	1.95	2.00	2.10		1.95	2.00	2.10	
D	13.65	13.90	14.15	4	13.65	13.90	14.15	4
D_1	9.90	10.00	10.10	7	9.90	10.00	10.10	7
D_3		8.00 REF.				7.80 REF.		
Z_D		1.00 REF.				1.10 REF.		
E	13.65	13.90	14.15	4	13.65	13.90	14.15	4
E_1	9.90	10.00	10.10	7	9.90	10.00	10.10	7
E_3		8.00 REF.				7.80 REF.		
Z_E		1.00 REF.				1.10 REF.		
L	0.73	0.88	1.03		0.73	0.88	1.03	
N		44				52		
e		0.80 BSC				0.65 BSC		
b	0.30		0.45		0.22		0.38	
b_1	0.30	0.35	0.40		0.22	0.30	0.33	
aaa		0.16				0.12		

VARIATIONS ALL DIMENSIONS IN INCHES

SYMBOL	BA MIN.	BA NOM.	BA MAX.	NOTE	BB MIN.	BB NOM.	BB MAX.	NOTE
A		.084	.093			.084	.093	
A_1	.004	.006	.010		.000	.006	.010	
A_2	.077	.079	.083		.077	.079	.083	
D	.537	.547	.557	4	.537	.547	.557	4
D_1	.390	.394	.398	7	.390	.394	.398	7
D_3		.315 REF.				.307 REF.		
Z_D		.039 REF.				.043 REF.		
E	.537	.547	.557	4	.537	.547	.557	4
E_1	.390	.394	.398	7	.390	.394	.398	7
E_3		.315 REF.				.307 REF.		
Z_E		.039 REF.				.043 REF.		
L	.029	.035	.046		.029	.035	.046	
N		44				52		
e		.0315 BSC				.0256 BSC		
b	.012		.018		.009		.015	
b_1	.012	.014	.016		.009	.012	.013	
aaa		.006				.005		

Amkor Technology, Inc.
Chandler, Arizona, USA
Anam Semiconductor, Inc.,
Seoul, Korea
Amkor Technology Philippines, Inc.
Manila, Philippines

Amkor Technology / ANAM Semiconductor

PACKAGE OUTLINE, MQFP, 10 X 10 MM BODY, 1.95/0.15 MM FORM, 2.00 MM THICK

SIZE	DWG NUMBER	REV
A3	32187	05

SCALE		SHEET
8:1	PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING	2 of 2

FORM NO. MDFORM4J.DWG